

Dual P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^{d, e}	Q _g (Typ.)			
- 30	0.029 at V _{GS} = - 10 V	- 7.3	17 nC			
- 30	0.039 at $V_{GS} = -4.5 \text{ V}$	- 6.3	17110			

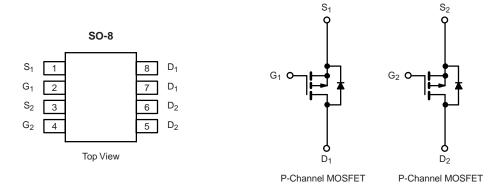
FEATURES

- Halogen-free
- TrenchFET® Power MOSFET
- 100 % UIS Tested



APPLICATIONS

· Load Switches



Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage		V_{GS}	± 20	V
	T _C = 25 °C		- 7.3 ^e	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 7.0 ^e	
Continuous Diam Current (1) = 130 °C)	T _A = 25 °C	l _D	- 7.3 ^{a, b}	
	T _A = 70 °C		- 5.9 ^{a, b}	A
Pulsed Drain Current	I _{DM}	- 32 ^e	A	
0 1 0 0 0 1	T _C = 25 °C	I.	- 4.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	ls —	- 2.0 ^{a, b}	
Avalanche Current	1 0.1 ml l	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		5.0	
Maximum Davian Disaination	T _C = 70 °C		3.2	w
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	VV
	T _A = 70 °C		1.6 ^{a, b}	
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	50	°C/W	
Maximum Junction-to-Foot	Steady State	R_{thJF}	20	25	C/VV	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on $T_C = 25$ °C.
- e. Limited by package.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250A		- 31		1400	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		4.5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
7 0	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1 - 5		
Zero Gate Voltage Drain Current		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C					
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
		V _{GS} = - 10 V, I _D = - 6.3 A		0.035		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 6.2 A		0.040			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 6.1 A		23		S	
Dynamic ^b	ı						
Input Capacitance	C _{iss}			1350		pF	
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		215			
Reverse Transfer Capacitance	C _{rss}			185			
Total Gate Charge		V _{DS} = -15 V, V _{GS} = -10 V, I _D = -6.1 A		32	50		
	Q_g			15	25		
Gate-Source Charge	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 6.1 A		4		nC	
Gate-Drain Charge	Q_{gd}			7.5			
Gate Resistance	R _g	f = 1 MHz		5.8		Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	ì,	$V_{DD} = -15 \text{ V}, R_{L} = 15 \Omega$		8	15		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 10 V, R_g = 1 Ω		45	70		
Fall Time	ì,	·		12	25		
Turn-On Delay Time	t _{d(on)}			42	70	ns	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 15 \Omega$		35	60	-	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		40	70		
Fall Time	t _f			16	30		
Drain-Source Body Diode Characterist	ics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1	۸	
Pulse Diode Forward Current	I _{SM}				- 32	Α	
Body Diode Voltage	V _{SD}	I _S = -2 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			34	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = - 2 A, dl/dt = 100 A/μs, T _J = 25 °C		22	40	nC	
Reverse Recovery Fall Time	t _a			11		200	
Reverse Recovery Rise Time	t _b			23		ns	

Notes:

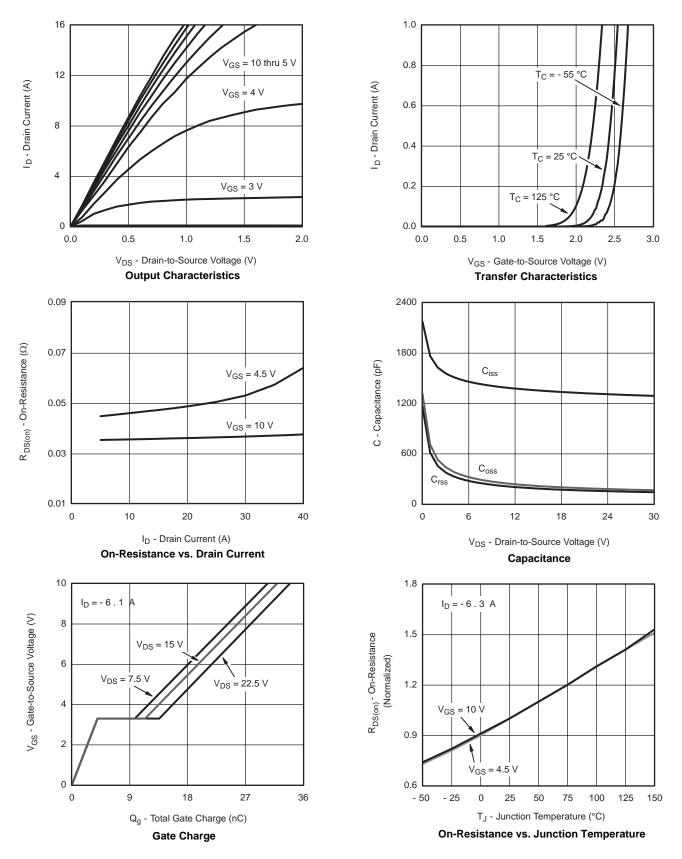
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

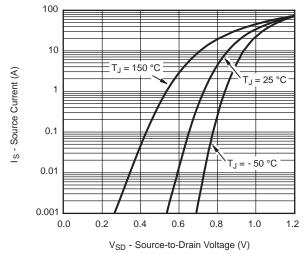


TYPICAL CHARACTERISTICS 25 C, unless otherwise noted

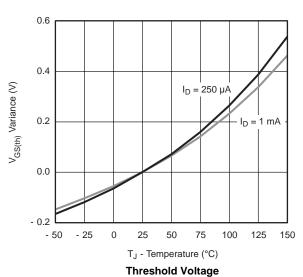


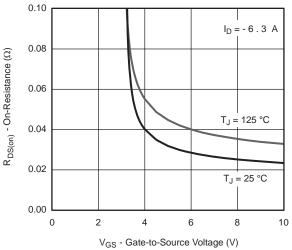


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

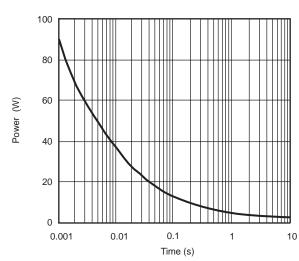


Source-Drain Diode Forward Voltage

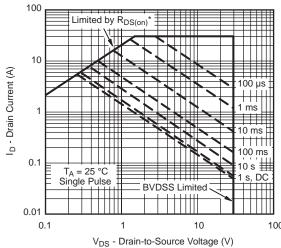




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

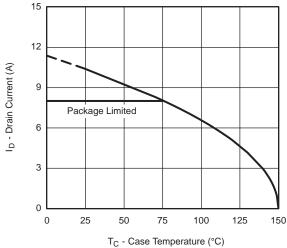


Safe Operating Area

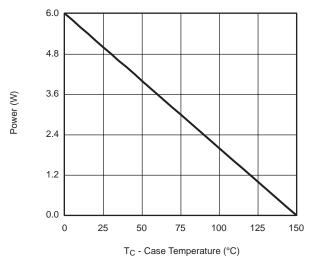
^{*} V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

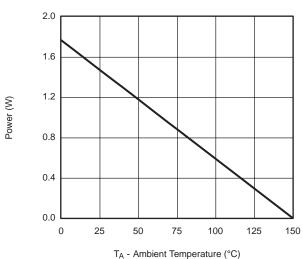


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*





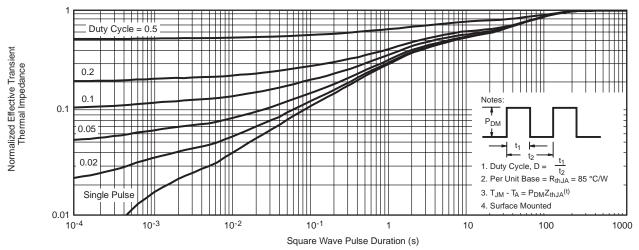
Power, Junction-to-Foot

Power Derating, Junction-to-Ambient

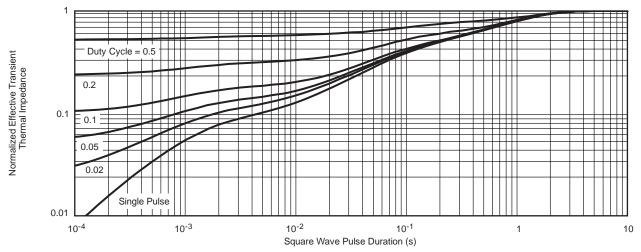
^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



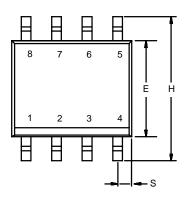
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIMETERS		INC	HES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
FCN: C-06527-Rev 11-Sen-06					

ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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